# PATENT ASSIGNMENT COVER SHEET

# Electronic Version v1.1 Stylesheet Version v1.2

# EPAS ID: PAT2643722

SUBMISSION TYPE				
NATURE OF CONVE	DNVEYANCE: ASSIGNMENT			
CONVEYING PART	Y DATA			
		Name	Execution Date	
JOHN CONTRERAS	6		12/09/2013	
SAURABH DEORAS	6		12/09/2013	
SAMIR GARZON			12/06/2013	
REMMELT PIT			12/06/2013	
CRAIG K. YANAGIS	AWA		12/09/2013	
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State/Country:		DS		
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	RS Total: 1			
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		H20131076US1		
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ATTORNEY DOCKE			PATENT	

NAME OF SUBMITTER:	JOAN PENNINGTON	
Signature:	/Joan Pennington/	
Date:	12/10/2013	
Total Attachments: 4 source=H20131076US1_Ex_Assignment-12-10-13#page1.tif source=H20131076US1_Ex_Assignment-12-10-13#page2.tif source=H20131076US1_Ex_Assignment-12-10-13#page3.tif source=H20131076US1_Ex_Assignment-12-10-13#page4.tif		

Whereas, I/we the undersigned inventor(s) have invented certain improvements as set forth in the patent application entitled:

### IMPLEMENTING CALIBRATION OF COOLING SENSITIVITY OF EMBEDDED CONTACT SENSOR (ECS) SIGNAL USING THERMAL FLY-HEIGHT CONTROL (TFC) ACTUATIONS

Whereas, **HGST Netherlands B.V.**, having a place of business at Herikerbergweg 238, Luna ArenA, 1101 CM Amsterdam, The Netherlands (hereinafter referred to as "HGST"), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefore;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, I/we, the above named, hereby sell, assign, and transfer to HGST, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to HGST, its successors and assigns; and we hereby agree that HGST may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by HGST.

Signed on the date(s) indicated beside my (our) signature(s).

Signature: X/10 Typed Name: John Contreras 1)

- 2) Signature: \_\_\_\_\_ Typed Name: Saurabh Deoras
- 3) Signature:
- 4) Signature: \_\_\_\_\_\_ Typed Name: Remmelt Pit
- 5) Signature: Typed Name: Craig K. Yanagisawa

Date: 12/9

Date:	

Date:	12/06/18	
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Date:

Date:

Docket No.: H20131076US1

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PATENT REEL: 031755 FRAME: 0164

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1)	Signature:
	Typed Name: John-Contreras

- 2) Signature: <u>Manhold</u> Typed Name: Saurabh Deoras
- 3) Signature: \_\_\_\_\_ Typed Name: Samir Garzon
- 4) Signature: \_\_\_\_\_\_ Typed Name: Remmelt Pit
- 5) Signature: Typed Name: Craig K. Yanagisawa

	Manager and a second
Date:	12/09/2013
Date:	
Date:	. <u></u>

Date:

Date:

Docket No.: H20131076US1

Page 1 of 1

PATENT REEL: 031755 FRAME: 0165

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<u>06/28/3</u>
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Docket No.: H20131076US1

Page 1 of 1

PATENT REEL: 031755 FRAME: 0166

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- Signature: 1) Typed Name: John Contreras
- Signature: (2)Typed Name: Saurabh Deoras
- Signature: 3) \_\_\_\_\_ Typed Name: Samir Garzon
- 4)
- Signature: Typed Name: Remmelt Pit Signature: Typed Name: Craig K. Vanagisawa 51

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Date:

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Date:

Date: 12-9-13

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PATENT REEL: 031755 FRAME: 0167

**RECORDED: 12/10/2013**